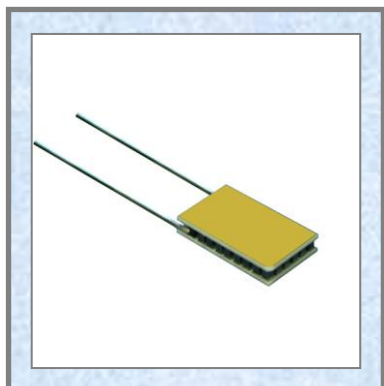


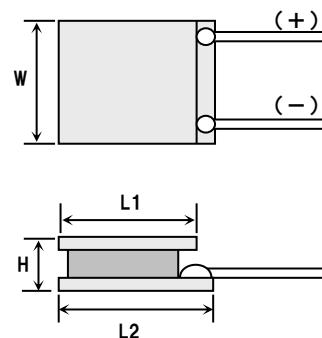
# THERMO MODULE DATA

Model **KSMH029**

( RoHS 2002/95/EC Compliant )



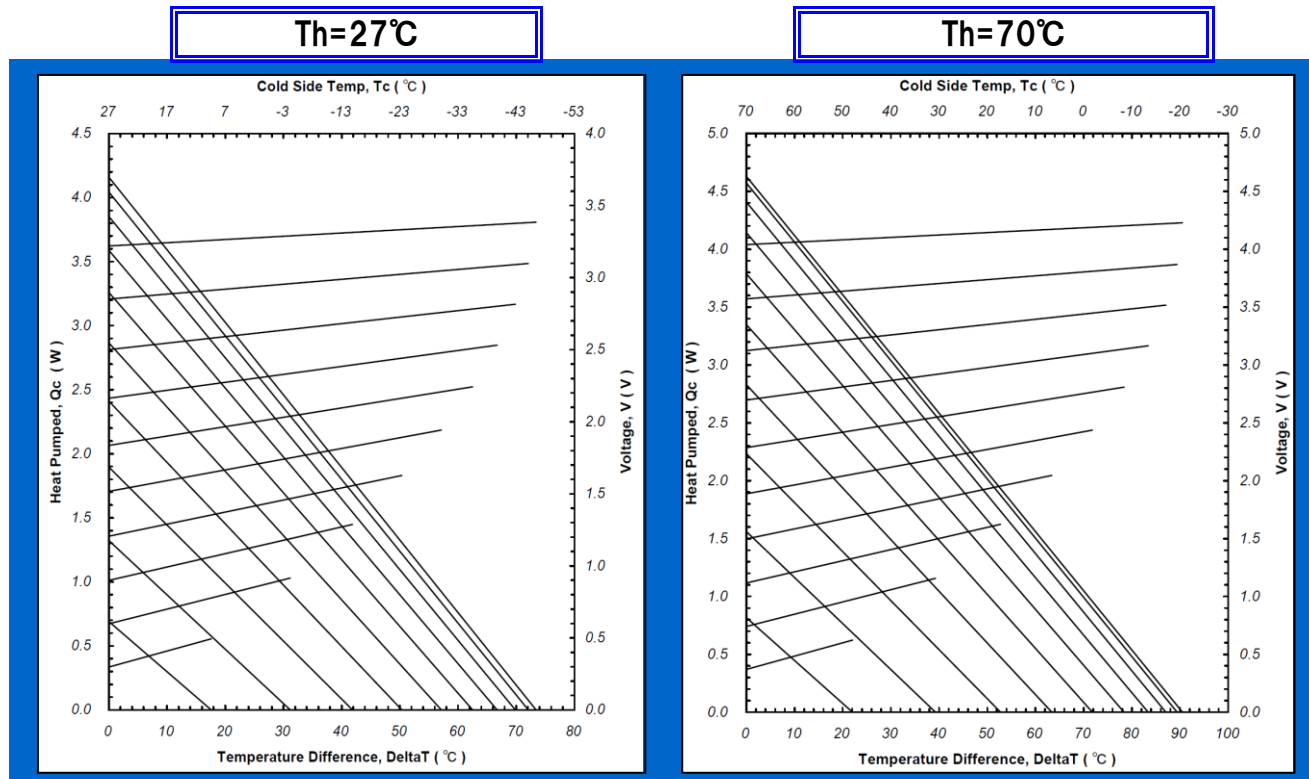
Th	$\Delta T_{max}(^{\circ}C)$	I <sub>max</sub> (A)	V <sub>max</sub> (v)	Q <sub>cmax</sub> (w)
27°C	75	2.0	3.4	4.1
70°C	93	2.0	4.3	4.6
Size(mm)	W	L1	L2	H
	6.0	10.2	10.2	1.65
Tolerance(mm)	±0.2	±0.2	±0.2	±0.1
Metallization	Cu-Ni-Au			
Ceramic material	Alumina			
Assembly solder	SnSb (melting point:232°C)			



## Option

Assembly solder	AuSn (melting point:280°C)
Ceramic material	All models can be assembled with alumina &/or aluminum nitride ceramics.
Pretinning solder	InSn(melting point:117°C),BiSn(melting point:138°C), SnAgCu(melting point:217°C)is also available, when AuSn is selected for assembly solder.

## Performance Diagram



Ambient	Nitrogen
Current value	I = 0.2 - 2.0 A ( Step = 0.20 A )

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